With more than 60 years of engineering experience SUSS MicroTec is a leading supplier of process equipment for microstructuring in the semiconductor industry and related markets. Our portfolio covers a comprehensive range of products and solutions for backend lithography, wafer bonding and photomask processing, complemented by micro-optical components.

SUSS MicroTec provides cost-effective solutions with unsurpassed quality and cutting-edge technology, enabling our customers to maximize yield at high throughput thus reducing cost of ownership.

In close cooperation with research institutes and industry partners SUSS MicroTec contributes to the advancement of next-generation technologies such as 3D Integration and Nanoimprint lithography as well as key processes for WLP, MEMS and LED manufacturing. With its global infrastructure for applications and service SUSS MicroTec supports more than 8,000 installed systems worldwide.

FACTS AND FIGURES

<table>
<thead>
<tr>
<th>IN € MILLION</th>
<th>2017</th>
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<tr>
<td>Order Entry</td>
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<td>Employees</td>
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MEMS (MicroElectroMechanical Systems) are key components in many automotive, industrial, medical, aerospace and consumer applications. MEMS sensors are used in anything from gaming, smartphones, medical testing to satellites. The applications seem unlimited. MEMS are everywhere.

Although based on commonly used Silicon wafer processing the manufacturing of MEMS devices requires highly specialized equipment to create mechanical structures that are a fraction of the width of a human hair. Highly flexible exposure and coating systems as well as wafer bonding equipment are essential in the processing of MEMS. From the start of volume manufacturing of MEMS products, SUSS MicroTec has been supplying equipment to the MEMS industry worldwide.

LEDs (Light Emitting Diode) are based on compound semiconductors (III-V) and widely used in optoelectronic devices, consumer electronics such as tablets and mobile phones, automotive and general lighting applications.

The manufacturing of LED devices requires dedicated equipment at lowest cost of ownership for this price-sensitive market. SUSS MicroTec provides exposure, coating, developing and wafer bonding equipment that handles fragile and highly warped wafers, deals with rough surfaces and provides best throughput for high volume manufacturing. Nanoimprint technologies are offered to manufacture specific layers for further light extraction efficiency.